PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7367906

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
BENJAMIN STASSEN COOK	10/21/2021
NAZILA DADVAND	09/14/2021
ARCHANA VENUGOPAL	01/24/2022
DANIEL LEE REVIER	09/20/2021

RECEIVING PARTY DATA

Name:	TEXAS INSTRUMENTS INCORPORATED
Street Address:	12500 TI BOULEVARD
City:	DALLAS
State/Country:	TEXAS
Postal Code:	75243

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17138541

CORRESPONDENCE DATA

Fax Number: (214)567-2228

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (214) 479-1264
Email: uspto@ti.com
Correspondent Name: TEXAS INSTRUMENTS INCORPORATED
Address Line 1: PO BOX 655474
Address Line 2: MS 3999
Address Line 4: DALLAS, TEXAS 75265

ATTORNEY DOCKET NUMBER:	TI-79470
NAME OF SUBMITTER:	TINA MATHEWSON
SIGNATURE:	/Tina Mathewson/
DATE SIGNED:	06/06/2022

Total Attachments: 6
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Application No. 17/138,541 Attorney Docket No. T79470US01

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made;

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard, M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon, as well as to U.S. Provisional Application No(s). , filed .

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my corresponding rights to the invention disclosed in said application in all other countries of the world, including the right to claim priority, file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

I authorize the later insertion of the nonprovisional application number and filing date hereinbelow.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE	THERMALLY CONDUCTIVE WAFER LAYER		
NONPROVISIONAL APPLICATION NO.	17/138,541	FILING DATE	12/30/2020

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Benjamin Stassen Cook
DATE	10/21/21
RESIDENCE (CITY AND STATE)	Los Gatos, CA United States

TITLE OF INVENTION	THERMALLY CONDUCTIVE WAFER LAYER
SIGNATURE OF INVENTOR	Nazila Dadvand
PRINTED NAME OF INVENTOR	Nazila Dadvand
DATE	9/14/2021
RESIDENCE (CITY AND STATE)	Santa Clara, CA

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Archana Venugopal
DATE	
RESIDENCE (CITY AND STATE)	Santa Clara, CA

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Daniel Lee Revier
DATE	
RESIDENCE (CITY AND STATE)	Garland, Texas

After recording, return Assignment to:

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265

Serial No. 17/138,541

Attorney Docket No.
TI-79470

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WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard, M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefore, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE	THERMALLY CONDUCTIVE WAFER LAYER		
NONPROVISIONAL APPLICATION NO.	17/138,541	FILING DATE	December 30, 2020

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Benjamin Stassen Cook
DATE	
RESIDENCE (CITY AND STATE)	Los Gatos, CA

TITLE OF INVENTION	THERMALLY CONDUCTIVE WAFER LAYER
SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Nazila Dadvand
DATE	
RESIDENCE (CITY AND STATE)	Santa Clara, CA

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Archana Venugopal
DATE	24 Jan 2022
RESIDENCE (CITY AND STATE)	Santa Clara, CA

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Daniel Lee Revier
DATE	
RESIDENCE (CITY AND STATE)	Garland, Texas

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DATE	
RESIDENCE (CITY AND STATE)	Santa Clara, CA

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Archana Venugopal
DATE	
RESIDENCE (CITY AND STATE)	Santa Clara, CA

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Daniel Lee Revier
DATE	9/20/21
RESIDENCE (CITY AND STATE)	~~Garland, Texas~~ DR Seattle, WA

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